LM193, LM293, LM293A
LM393, LM393A, LM2903, LM2903V

Dual Differential Comparators

Check for Samples: LM193, LM293, LM293A, LM393, LM393A, LM2903, LM2903V

FEATURES

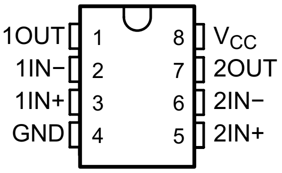
- **Single Supply or Dual Supplies**
- **Wide Range of Supply Voltage**
  - **Max Rating: 2 V to 36 V**
  - **Tested to 30 V: Non-V Devices**
  - **Tested to 32 V: V-Suffix Devices**
- **Low Supply-Current Drain Independent of Supply Voltage: 0.4 mA (Typ) Per Comparator**
- **Low Input Bias Current: 25 nA (Typ)**
- **Low Input Offset Current: 3 nA (Typ) (LM139)**
- **Low Input Offset Voltage: 2 mV (Typ)**
- **Common-Mode Input Voltage Range Includes Ground**
- **Differential Input Voltage Range Equal to Maximum-Rated Supply Voltage: ±36 V**
- **Low Output Saturation Voltage**
- **Output Compatible With TTL, MOS, and CMOS**
- **On Products Compliant to MIL-PRF-38535, All Parameters Are Tested Unless Otherwise Noted. On All Other Products, Production Processing Does Not Necessarily Include Testing of All Parameters.**

DESCRIPTION

These devices consist of two independent voltage comparators that are designed to operate from a single power supply over a wide range of voltages. Operation from dual supplies also is possible as long as the difference between the two supplies is 2 V to 36 V, and V_{CC} is at least 1.5 V more positive than the input common-mode voltage. Current drain is independent of the supply voltage. The outputs can be connected to other open-collector outputs to achieve wired-AND relationships.

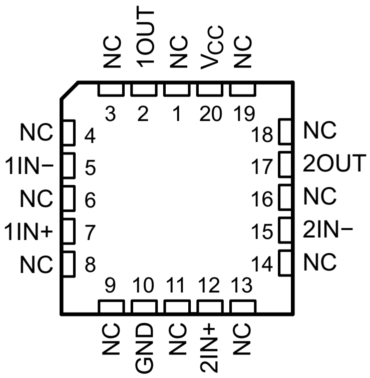
The LM193 is characterized for operation from −55°C to 125°C. The LM293 and LM293A are characterized for operation from −25°C to 85°C. The LM393 and LM393A are characterized for operation from 0°C to 70°C. The LM2903 is characterized for operation from −40°C to 125°C.

LM193 . . . D OR JG PACKAGE
LM293 . . . D, DGK, OR P PACKAGE
LM293A . . . DOR DGK PACKAGE
LM393, LM393A . . . D, DGK, P, PS, OR PW PACKAGE
LM2903 . . . D, DGK, P, PS, OR PW PACKAGE
(TOP VIEW)



NC − No internal connection

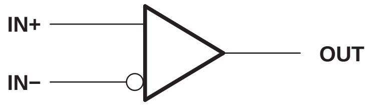
LM193 . . . FK PACKAGE
(TOP VIEW)



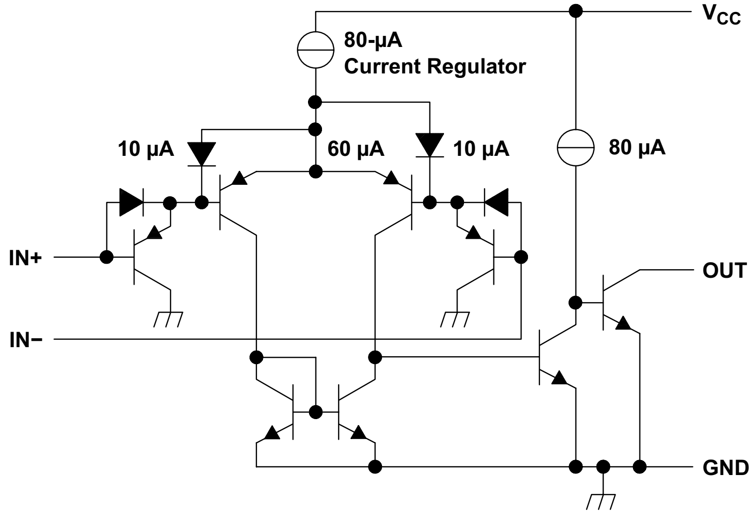
This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

Symbol (Each Comparator)



Schematic (Each Comparator)



COMPONENT COUNT	
Epi-FET	1
Diodes	2
Resistors	2
Transistors	30

Current values shown are nominal.

Absolute Maximum Ratings(1)

over operating free-air temperature range (unless otherwise noted)

		VALUE	UNIT
Supply voltage, V_{CC}(2)		36	V
Differential input voltage, V_{ID}(3)		±36	V
Input voltage range (either input), V_I		–0.3 to 36	V
Output voltage, V_O		36	V
Output current, I_O		20	mA
Duration of output short circuit to ground(4)		Unlimited	
Package thermal impedance, junction to free air, θ_{JA}(5)(6)	D package	97	°C/W
	DGK package	172	
	P package	85	
	PS package	95	
	PW package	149	
Package thermal impedance, junction to case, θ_{JC}(7)(8)	FK package	5.61	°C/W
	JG package	14.5	
Operating virtual-junction temperature, T_J		150	°C
Case temperature for 60 s	FK package	260	°C
Lead temperature 1,6 mm (1/16 in) from case for 60 s	J package	300	°C
Storage temperature range, T_{stg}		–65 to 150	°C

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) All voltage values, except differential voltages, are with respect to network ground.
(3) Differential voltages are at IN+ with respect to IN–.
(4) Short circuits from outputs to V_{CC} can cause excessive heating and eventual destruction.
(5) Maximum power dissipation is a function of T_J (max), θ_{JA}, and T_A. The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J \text{ (max)} – T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
(6) The package thermal impedance is calculated in accordance with JESD 51-7.
(7) Maximum power dissipation is a function of T_J (max), θ_{JC}, and T_C. The maximum allowable power dissipation at any allowable case temperature is $P_D = (T_J \text{ (max)} – T_C)/\theta_{JC}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
(8) The package thermal impedance is calculated in accordance with MIL-STD-883.

Electrical Characteristics

at specified free-air temperature, V_{CC} = 5 V (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T_A[1]	LM193			LM293 LM393			UNIT
					MIN	TYP	MAX	MIN	TYP	MAX	
V_{IO}	Input offset voltage	V_{CC} = 5 V to 30 V, $V_{IC} = V_{ICR}$ min, V_O = 1.4 V		25°C		2	5		2	5	mV
				Full range			9			9	
I_{IO}	Input offset current	V_O = 1.4 V		25°C		3	25		5	50	nA
				Full range			100			250	
I_{IB}	Input bias current	V_O = 1.4 V		25°C		–25	–100		–25	–250	nA
				Full range			–300			–400	
V_{ICR}	Common-mode input-voltage range[2]			25°C	0 to V_{CC} – 1.5			0 to V_{CC} – 1.5			V
				Full range	0 to V_{CC} – 2			0 to V_{CC} – 2			
A_{VD}	Large-signal differential-voltage amplification	V_{CC} = 15 V, V_O = 1.4 V to 11.4 V, R_L ≥ 15 kΩ to V_{CC}		25°C	50	200		50	200		V/mV
I_{OH}	High-level output current	V_{OH} = 5 V	V_{ID} = 1 V	25°C		0.1			0.1	50	nA
		V_{OH} = 30 V	V_{ID} = 1 V	Full range			1			1	μA
V_{OL}	Low-level output voltage	I_{OL} = 4 mA,	V_{ID} = –1 V	25°C		150	400		150	400	mV
				Full range			700			700	
I_{OL}	Low-level output current	V_{OL} = 1.5 V,	V_{ID} = –1 V	25°C	6			6			mA
I_{CC}	Supply current	R_L = ∞	V_{CC} = 5 V	25°C		0.8	1		0.8	1	mA
			V_{CC} = 30 V	Full range			2.5			2.5	

(1) Full range (MIN or MAX) for LM193 is –55°C to 125°C, for LM293 is 25°C to 85°C, and for LM393 is 0°C to 70°C. All characteristics are measured with zero common-mode input voltage, unless otherwise specified.

(2) The voltage at either input or common-mode should not be allowed to go negative by more than 0.3 V. The upper end of the common-mode voltage range is V_{CC}+ – 1.5 V for the inverting input (–), and the non-inverting input (+) can exceed the V_{CC} level; the comparator provides a proper output state. Either or both inputs can go to 30 V without damage.

Electrical Characteristics

at specified free-air temperature, V_{CC} = 5 V (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T_A [1]	LM293A LM393A			UNIT
					MIN	TYP	MAX	
V_{IO}	Input offset voltage	V_{CC} = 5 V to 30 V, V_O = 1.4 V $V_{IC} = V_{ICR(min)}$		25°C		1	2	mV
				Full range			4	
I_{IO}	Input offset current	V_O = 1.4 V		25°C		5	50	nA
				Full range			150	
I_{IB}	Input bias current	V_O = 1.4 V		25°C		–25	–250	nA
				Full range			–400	
V_{ICR}	Common-mode input-voltage range [2]			25°C	0 to V_{CC} – 1.5			V
				Full range	0 to V_{CC} – 2			
A_{VD}	Large-signal differential-voltage amplification	V_{CC} = 15 V, V_O = 1.4 V to 11.4 V, R_L ≥ 15 kΩ to V_{CC}		25°C	50	200		V/mV
I_{OH}	High-level output current	V_{OH} = 5 V,	V_{ID} = 1 V	25°C		0.1	50	nA
		V_{OH} = 30 V,	V_{ID} = 1 V	Full range			1	μA
V_{OL}	Low-level output voltage	I_{OL} = 4 mA,	V_{ID} = –1 V	25°C		150	400	mV
				Full range			700	
I_{OL}	Low-level output current	V_{OL} = 1.5 V,	V_{ID} = –1 V,	25°C	6			mA
I_{CC}	Supply current (four comparators)	R_L = ∞	V_{CC} = 5 V	25°C		0.8	1	mA
			V_{CC} = 30 V	Full range			2.5	

(1) Full range (MIN or MAX) for LM293A is 25°C to 85°C, and for LM393A is 0°C to 70°C. All characteristics are measured with zero common-mode input voltage, unless otherwise specified.

(2) The voltage at either input or common-mode should not be allowed to go negative by more than 0.3 V. The upper end of the common-mode voltage range is V_{CC+} – 1.5 V, but either or both inputs can go to 30 V without damage.

Electrical Characteristics

at specified free-air temperature, V_{CC} = 5 V (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T_A (1)	LM2903			LM2903A			UNIT
					MIN	TYP	MAX	MIN	TYP	MAX	
V_{IO}	Input offset voltage	V_{CC} = 5 V to MAX (2) , V_O = 1.4 V, V_{IC} = $V_{ICR(min)}$,		25°C		2	7		1	2	mV
				Full range			15			4	
I_{IO}	Input offset current	V_O = 1.4 V		25°C		5	50		5	50	nA
				Full range			200			200	
I_{IB}	Input bias current	V_O = 1.4 V		25°C		–25	–250		–25	–250	nA
				Full range			–500			–500	
V_{ICR}	Common-mode input-voltage range (3)			25°C	0 to V_{CC} – 1.5			0 to V_{CC} – 1.5			V
				Full range	0 to V_{CC} – 2			0 to V_{CC} – 2			
A_{VD}	Large-signal differential-voltage amplification	V_{CC} = 15 V, V_O = 1.4 V to 11.4 V, R_L ≥ 15 kΩ to V_{CC}		25°C	25	100		25	100		V/mV
I_{OH}	High-level output current	V_{OH} = 5 V,	V_{ID} = 1 V	25°C		0.1	50		0.1	50	nA
		V_{OH} = V_{CC} MAX (2),	V_{ID} = 1 V	Full range			1			1	μA
V_{OL}	Low-level output voltage	I_{OL} = 4 mA,	V_{ID} = –1 V,	25°C		150	400		150	400	mV
				Full range			700			700	
I_{OL}	Low-level output current	V_{OL} = 1.5 V,	V_{ID} = –1 V	25°C	6			6			mA
I_{CC}	Supply current	R_L = ∞	V_{CC} = 5 V	25°C		0.8	1		0.8	1	mA
			V_{CC} = MAX	Full range			2.5			2.5	

(1) Full range (MIN or MAX) for LM2903 is –40°C to 125°C. All characteristics are measured with zero common-mode input voltage, unless otherwise specified.
(2) V_{CC} MAX = 30 V for non-V devices and 32 V for V-suffix devices.
(3) The voltage at either input or common-mode should not be allowed to go negative by more than 0.3 V. The upper end of the common-mode voltage range is V_{CC+} – 1.5 V, but either or both inputs can go to 30 V (32 V for V-suffix devices) without damage.

Switching Characteristics

V_{CC} = 5 V, T_A = 25°C

PARAMETER	TEST CONDITIONS		LM2901, LM293, LM293A LM393, LM393A LM2903	UNIT
			TYP	
Response time	R_L connected to 5 V through 5.1 kΩ, C_L = 15 pF (1) (2)	100-mV input step with 5-mV overdrive	1.3	μs
		TTL-level input step	0.3	

(1) C_L includes probe and jig capacitance.
(2) The response time specified is the interval between the input step function and the instant when the output crosses 1.4 V.

REVISION HISTORY

Changes from Revision W (July 2010) to Revision X	Page
• Updated document to new TI data sheet format - no specification changes.	1
• Updated Features.	1
• Added ESD warning.	2
• Removed Ordering Information table.	2

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9452601Q2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 9452601Q2A LM193FKB	Samples
5962-9452601QPA	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type	-55 to 125	9452601QPA LM193	Samples
JM38510/11202BPA	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510 /11202BPA	Samples
LM193DR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	LM193	Samples
LM193DRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	LM193	Samples
LM193FKB	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 9452601Q2A LM193FKB	Samples
LM193JG	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type	-55 to 125	LM193JG	Samples
LM193JGB	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type	-55 to 125	9452601QPA LM193	Samples
LM2903AVQDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2903AV	Samples
LM2903AVQDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2903AV	Samples
LM2903AVQPWR	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2903AV	Samples
LM2903AVQPWRG4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2903AV	Samples
LM2903D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	LM2903	Samples
LM2903DE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	LM2903	Samples
LM2903DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	LM2903	Samples
LM2903DGKR	ACTIVE	VSSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU | CU NIPDAUAG	Level-1-260C-UNLIM	-40 to 125	(MAP ~ MAS ~ MAU)	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
LM2903DGKRG4	ACTIVE	VSSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	(MAP ~ MAS ~ MAU)	Samples
LM2903DR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU | CU SN	Level-1-260C-UNLIM	-40 to 125	LM2903	Samples
LM2903DRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	LM2903	Samples
LM2903DRG3	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	LM2903	Samples
LM2903DRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	LM2903	Samples
LM2903P	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 125	LM2903P	Samples
LM2903PE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 125	LM2903P	Samples
LM2903PSR	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2903	Samples
LM2903PSRG4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2903	Samples
LM2903PWLE	OBSOLETE	TSSOP	PW	8		TBD	Call TI	Call TI	-40 to 125		
LM2903PWR	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU | CU SN	Level-1-260C-UNLIM	-40 to 125	L2903	Samples
LM2903PWRE4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2903	Samples
LM2903PWRG3	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	L2903	Samples
LM2903PWRG4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2903	Samples
LM2903QD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	2903Q	Samples
LM2903QDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	2903Q	Samples
LM2903QDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	2903Q	Samples
LM2903QP	OBSOLETE	PDIP	P	8		TBD	Call TI	Call TI	-40 to 125		
LM2903VQDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2903V	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
LM2903VQDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2903V	Samples
LM2903VQPWR	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2903V	Samples
LM2903VQPWRG4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2903V	Samples
LM293AD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	LM293A	Samples
LM293ADE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	LM293A	Samples
LM293ADG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	LM293A	Samples
LM293ADGKR	ACTIVE	VSSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU | CU NIPDAUAG	Level-1-260C-UNLIM	-25 to 85	(MDP ~ MDS ~ MDU)	Samples
LM293ADGKRG4	ACTIVE	VSSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	(MDP ~ MDS ~ MDU)	Samples
LM293ADR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU | CU SN	Level-1-260C-UNLIM	-25 to 85	LM293A	Samples
LM293ADRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	LM293A	Samples
LM293D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	LM293	Samples
LM293DE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	LM293	Samples
LM293DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	LM293	Samples
LM293DGKR	ACTIVE	VSSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU | CU NIPDAUAG	Level-1-260C-UNLIM	-25 to 85	(MCP ~ MCS ~ MCU)	Samples
LM293DGKRG4	ACTIVE	VSSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	(MCP ~ MCS ~ MCU)	Samples
LM293DR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU | CU SN	Level-1-260C-UNLIM	-25 to 85	LM293	Samples
LM293DRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	LM293	Samples
LM293DRG3	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-25 to 85	LM293	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
LM293DRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	LM293	Samples
LM293P	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU | CU SN	N / A for Pkg Type	-25 to 85	LM293P	Samples
LM293PE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-25 to 85	LM293P	Samples
LM393AD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM393A	Samples
LM393ADE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM393A	Samples
LM393ADG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM393A	Samples
LM393ADGKR	ACTIVE	VSSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU | CU NIPDAUAG	Level-1-260C-UNLIM	0 to 70	(M8P ~ M8S ~ M8U)	Samples
LM393ADGKRG4	ACTIVE	VSSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	(M8P ~ M8S ~ M8U)	Samples
LM393ADR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU | CU SN	Level-1-260C-UNLIM	0 to 70	LM393A	Samples
LM393ADRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM393A	Samples
LM393ADRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM393A	Samples
LM393AP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU | CU SN	N / A for Pkg Type	0 to 70	LM393AP	Samples
LM393APE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	LM393AP	Samples
LM393APSR	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	L393A	Samples
LM393APSRE4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	L393A	Samples
LM393APSRG4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	L393A	Samples
LM393APWLE	OBSOLETE	TSSOP	PW	8		TBD	Call TI	Call TI	0 to 70		
LM393APWR	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU | CU SN	Level-1-260C-UNLIM	0 to 70	L393A	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
LM393APWRE4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	L393A	Samples
LM393APWRG4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	L393A	Samples
LM393D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM393	Samples
LM393DE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM393	Samples
LM393DG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM393	Samples
LM393DGKR	ACTIVE	VSSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU | CU NIPDAUAG	Level-1-260C-UNLIM	0 to 70	(M9P ~ M9S ~ M9U)	Samples
LM393DGKRG4	ACTIVE	VSSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	(M9P ~ M9S ~ M9U)	Samples
LM393DR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU | CU SN	Level-1-260C-UNLIM	0 to 70	LM393	Samples
LM393DRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM393	Samples
LM393DRG3	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	0 to 70	LM393	Samples
LM393DRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM393	Samples
LM393P	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU | CU SN	N / A for Pkg Type	0 to 70	LM393P	Samples
LM393PE3	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	0 to 70	LM393P	Samples
LM393PE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	LM393P	Samples
LM393PSLE	OBSOLETE	SO	PS	8		TBD	Call TI	Call TI	0 to 70		
LM393PSR	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	L393	Samples
LM393PSRG4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	L393	Samples
LM393PW	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	L393	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
LM393PWG4	ACTIVE	TSSOP	PW	8	150	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	L393	Samples
LM393PWLE	OBSOLETE	TSSOP	PW	8		TBD	Call TI	Call TI	0 to 70		
LM393PWR	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU | CU SN	Level-1-260C-UNLIM	0 to 70	L393	Samples
LM393PWRG3	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	0 to 70	L393	Samples
LM393PWRG4	ACTIVE	TSSOP	PW	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	L393	Samples
M38510/11202BPA	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510 /11202BPA	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF LM2903, LM293 :

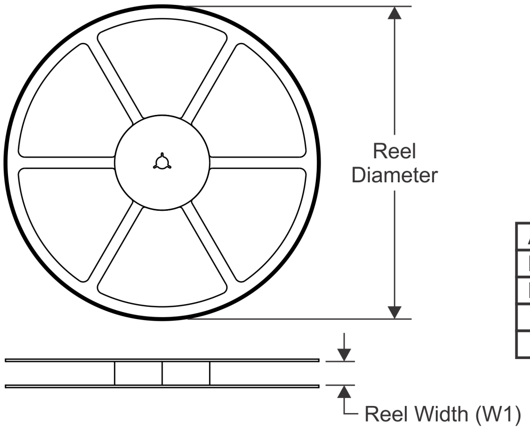
- Automotive: LM2903-Q1
- Enhanced Product: LM293-EP

NOTE: Qualified Version Definitions:

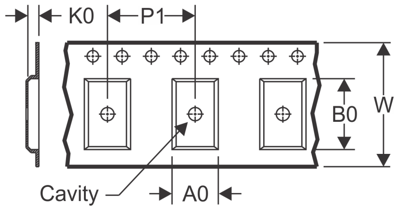
- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Enhanced Product - Supports Defense, Aerospace and Medical Applications

TAPE AND REEL INFORMATION

REEL DIMENSIONS

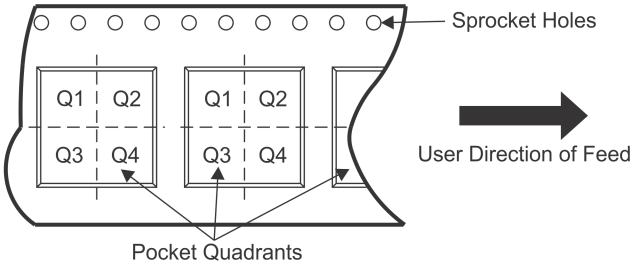


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

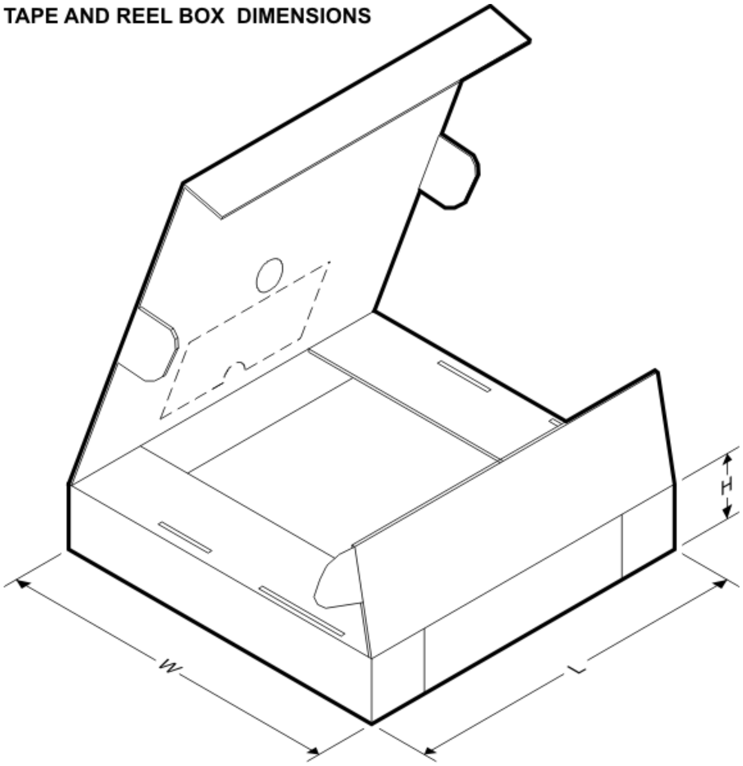


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM193DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM2903DGKR	VSSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
LM2903DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM2903DR	SOIC	D	8	2500	330.0	12.8	6.4	5.2	2.1	8.0	12.0	Q1
LM2903DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM2903DRG3	SOIC	D	8	2500	330.0	12.8	6.4	5.2	2.1	8.0	12.0	Q1
LM2903DRG4	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM2903DRG4	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM2903PSR	SO	PS	8	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
LM2903PWR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
LM2903PWR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
LM2903PWRG3	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
LM2903QDRG4	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM2903VQPWRG4	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
LM293ADGKR	VSSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
LM293ADR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM293ADR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM293ADRG4	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM293ADRG4	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM293DGKR	VSSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
LM293DR	SOIC	D	8	2500	330.0	12.8	6.4	5.2	2.1	8.0	12.0	Q1
LM293DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM293DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM293DRG3	SOIC	D	8	2500	330.0	12.8	6.4	5.2	2.1	8.0	12.0	Q1
LM293DRG4	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM293DRG4	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM393ADGKR	VSSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
LM393ADR	SOIC	D	8	2500	330.0	12.8	6.4	5.2	2.1	8.0	12.0	Q1
LM393ADR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM393ADR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM393ADRG4	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM393ADRG4	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM393APSR	SO	PS	8	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
LM393APWR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
LM393DGKR	VSSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
LM393DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM393DR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM393DRG3	SOIC	D	8	2500	330.0	12.8	6.4	5.2	2.1	8.0	12.0	Q1
LM393DRG4	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM393DRG4	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
LM393PSR	SO	PS	8	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
LM393PWR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
LM393PWRG3	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS

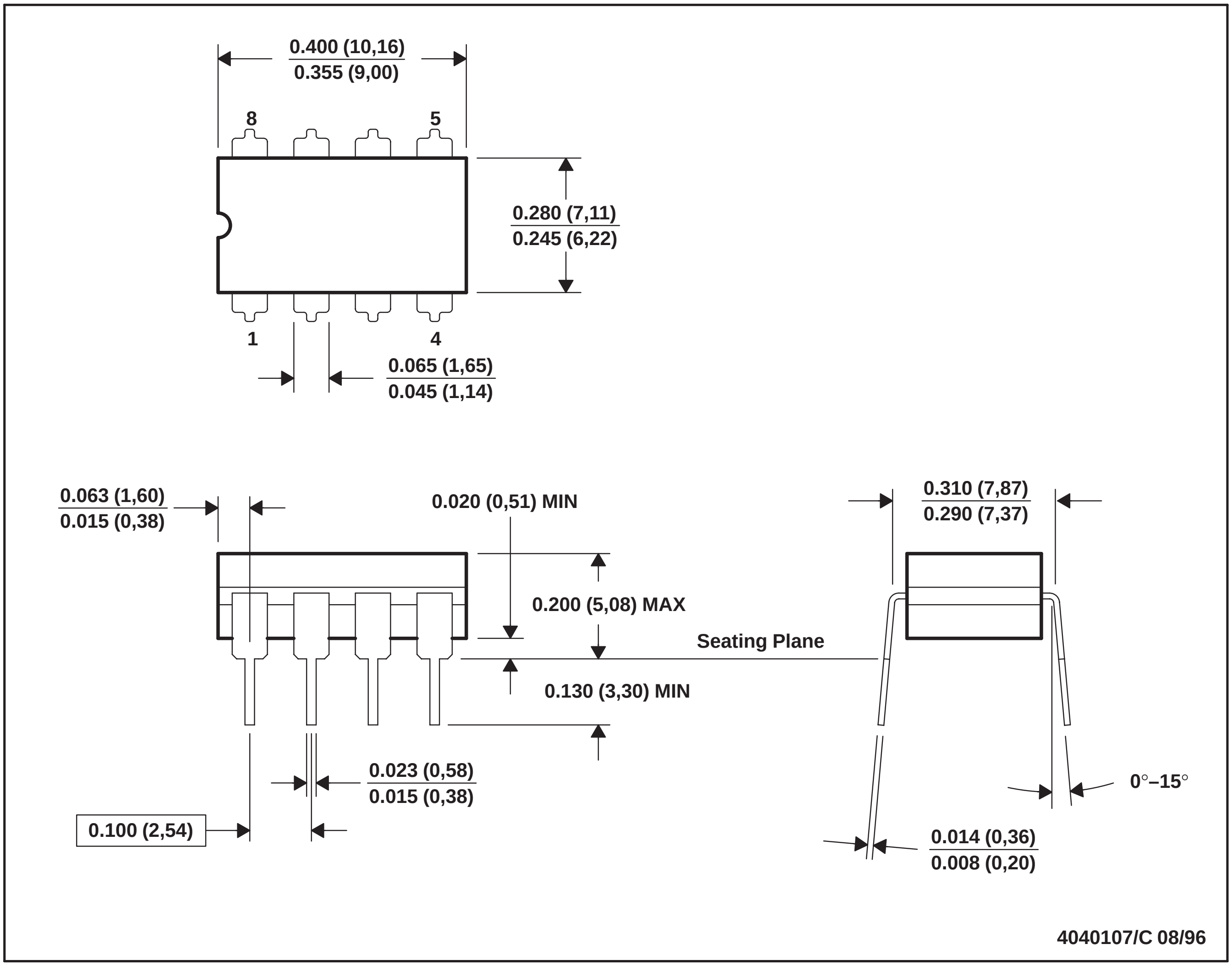


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM193DR	SOIC	D	8	2500	367.0	367.0	35.0
LM2903DGKR	VSSOP	DGK	8	2500	364.0	364.0	27.0
LM2903DR	SOIC	D	8	2500	340.5	338.1	20.6
LM2903DR	SOIC	D	8	2500	364.0	364.0	27.0
LM2903DR	SOIC	D	8	2500	367.0	367.0	35.0
LM2903DRG3	SOIC	D	8	2500	364.0	364.0	27.0
LM2903DRG4	SOIC	D	8	2500	340.5	338.1	20.6
LM2903DRG4	SOIC	D	8	2500	367.0	367.0	35.0
LM2903PSR	SO	PS	8	2000	367.0	367.0	38.0
LM2903PWR	TSSOP	PW	8	2000	367.0	367.0	35.0
LM2903PWR	TSSOP	PW	8	2000	364.0	364.0	27.0
LM2903PWRG3	TSSOP	PW	8	2000	364.0	364.0	27.0
LM2903QDRG4	SOIC	D	8	2500	367.0	367.0	35.0
LM2903VQPWRG4	TSSOP	PW	8	2000	367.0	367.0	35.0
LM293ADGKR	VSSOP	DGK	8	2500	364.0	364.0	27.0
LM293ADR	SOIC	D	8	2500	340.5	338.1	20.6
LM293ADR	SOIC	D	8	2500	367.0	367.0	35.0
LM293ADRG4	SOIC	D	8	2500	340.5	338.1	20.6
LM293ADRG4	SOIC	D	8	2500	367.0	367.0	35.0
LM293DGKR	VSSOP	DGK	8	2500	364.0	364.0	27.0

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM293DR	SOIC	D	8	2500	364.0	364.0	27.0
LM293DR	SOIC	D	8	2500	367.0	367.0	35.0
LM293DR	SOIC	D	8	2500	340.5	338.1	20.6
LM293DRG3	SOIC	D	8	2500	364.0	364.0	27.0
LM293DRG4	SOIC	D	8	2500	367.0	367.0	35.0
LM293DRG4	SOIC	D	8	2500	340.5	338.1	20.6
LM393ADGKR	VSSOP	DGK	8	2500	364.0	364.0	27.0
LM393ADR	SOIC	D	8	2500	364.0	364.0	27.0
LM393ADR	SOIC	D	8	2500	367.0	367.0	35.0
LM393ADR	SOIC	D	8	2500	340.5	338.1	20.6
LM393ADRG4	SOIC	D	8	2500	367.0	367.0	35.0
LM393ADRG4	SOIC	D	8	2500	340.5	338.1	20.6
LM393APSR	SO	PS	8	2000	367.0	367.0	38.0
LM393APWR	TSSOP	PW	8	2000	364.0	364.0	27.0
LM393DGKR	VSSOP	DGK	8	2500	364.0	364.0	27.0
LM393DR	SOIC	D	8	2500	367.0	367.0	35.0
LM393DR	SOIC	D	8	2500	340.5	338.1	20.6
LM393DRG3	SOIC	D	8	2500	364.0	364.0	27.0
LM393DRG4	SOIC	D	8	2500	367.0	367.0	35.0
LM393DRG4	SOIC	D	8	2500	340.5	338.1	20.6
LM393PSR	SO	PS	8	2000	367.0	367.0	38.0
LM393PWR	TSSOP	PW	8	2000	364.0	364.0	27.0
LM393PWRG3	TSSOP	PW	8	2000	364.0	364.0	27.0

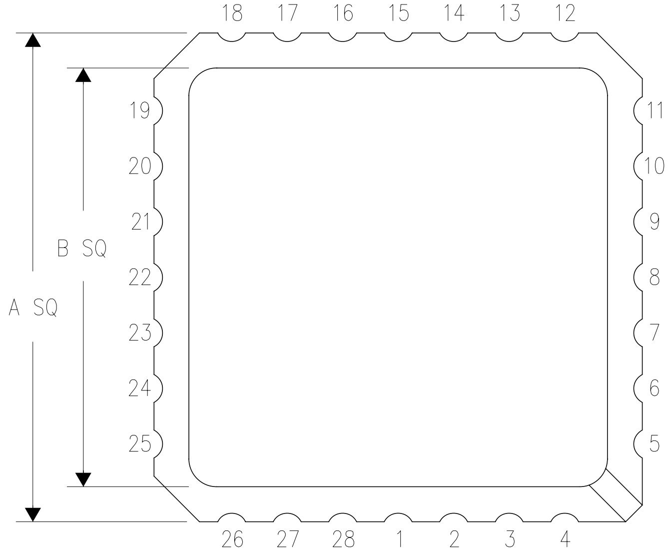
JG (R-GDIP-T8) CERAMIC DUAL-IN-LINE



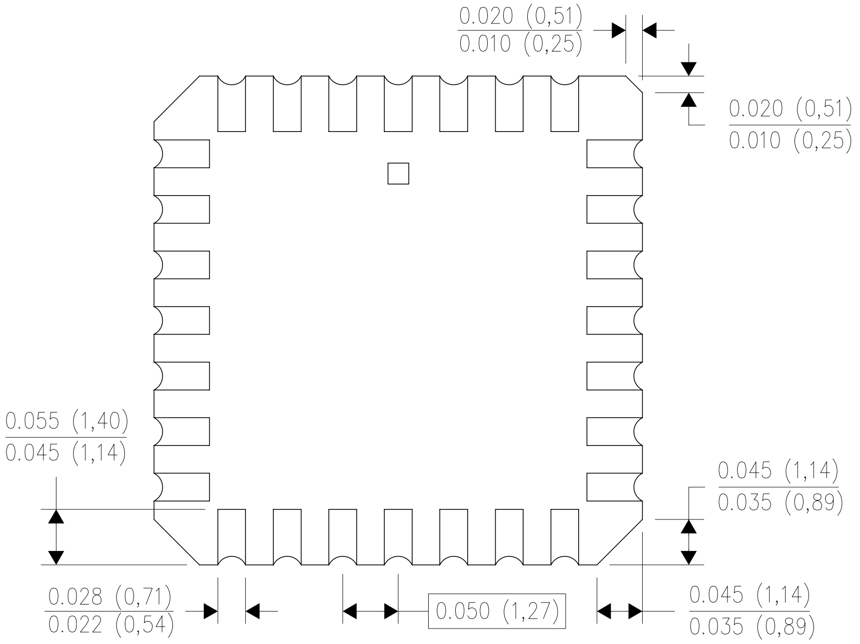
NOTES:
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification.
- E. Falls within MIL STD 1835 GDIP1-T8

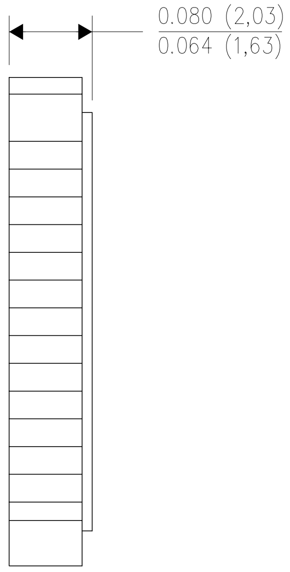
FK (S-CQCC-N**) LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)

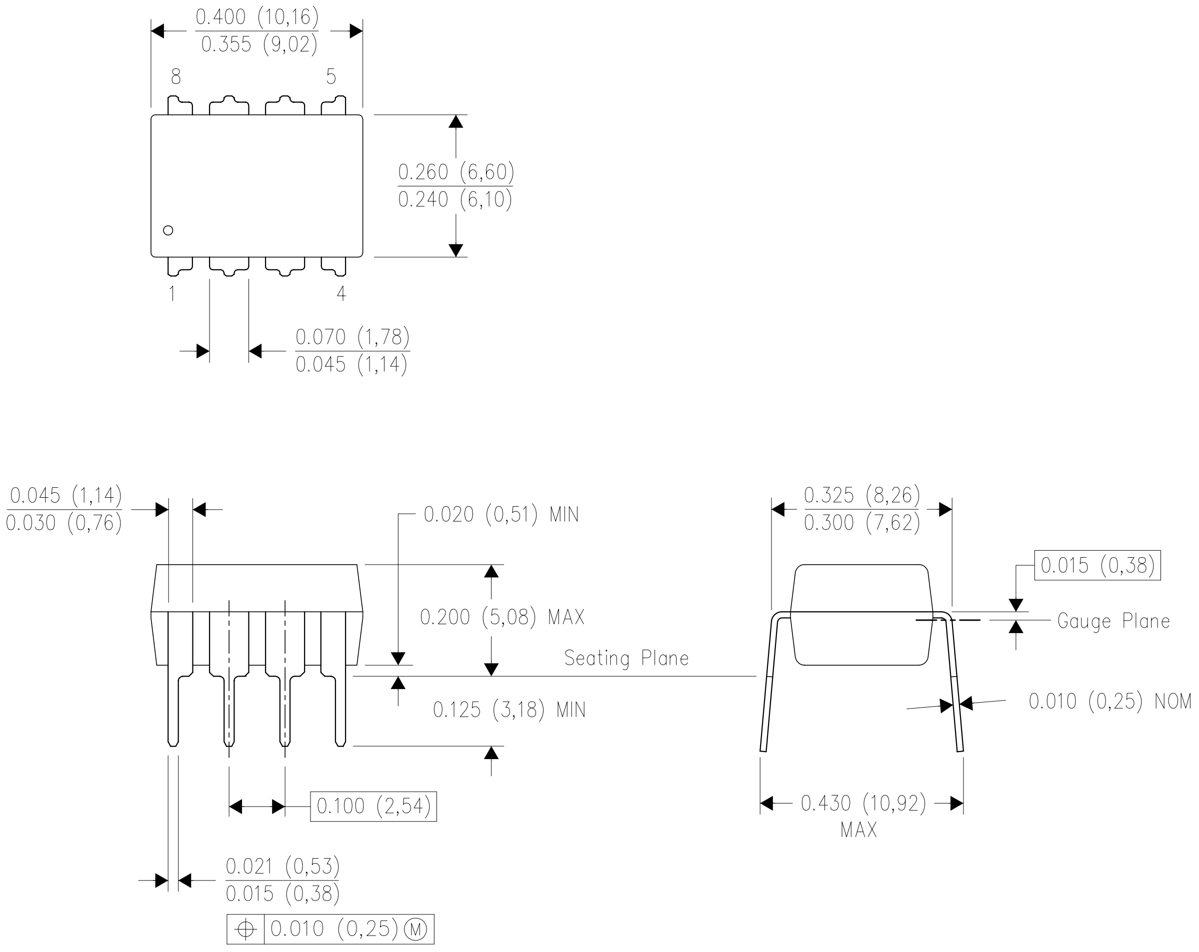




4040140/D 01/11

NOTES:
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS–004

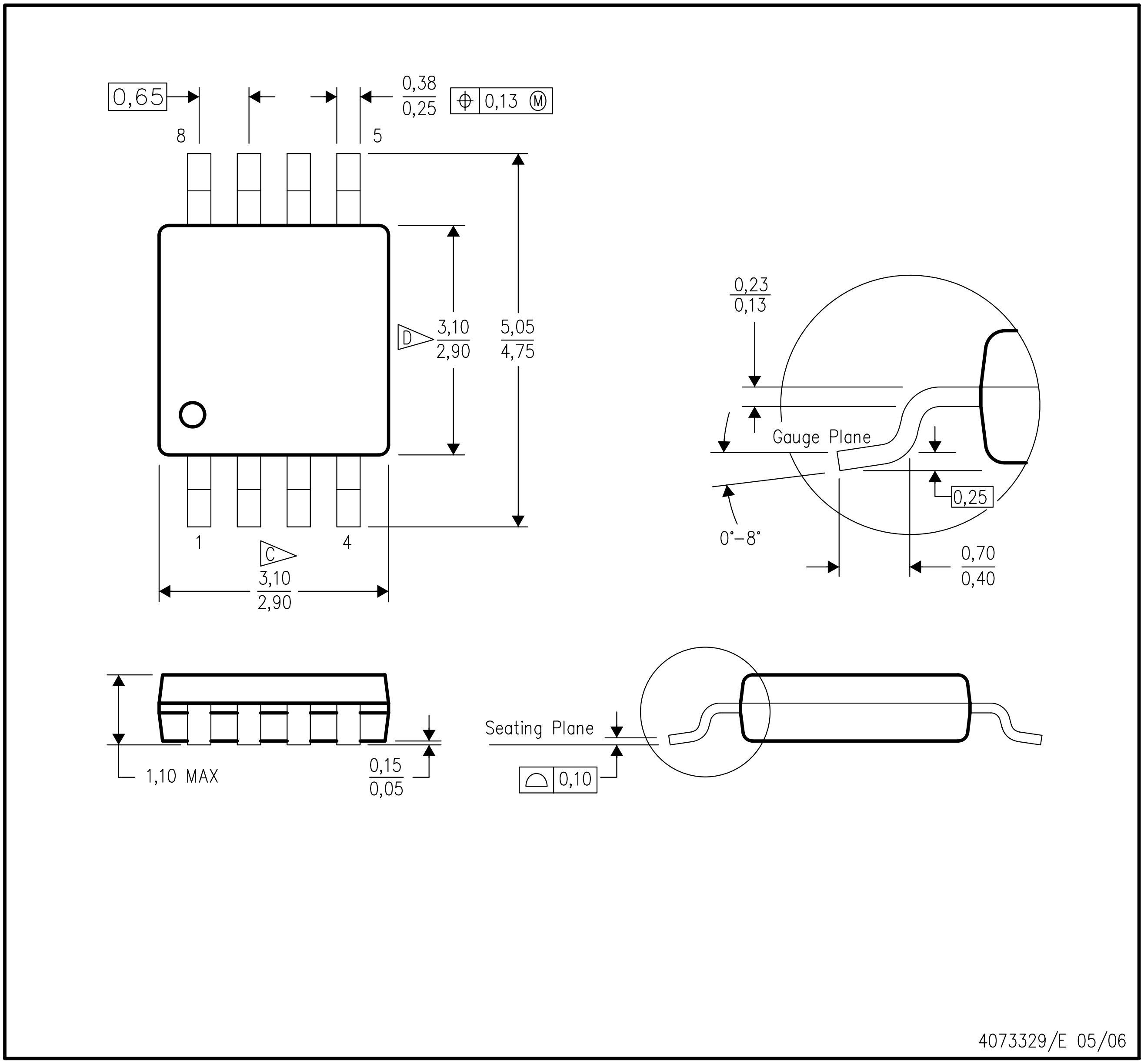
P (R–PDIP–T8) PLASTIC DUAL–IN–LINE PACKAGE



4040082/E 04/2010

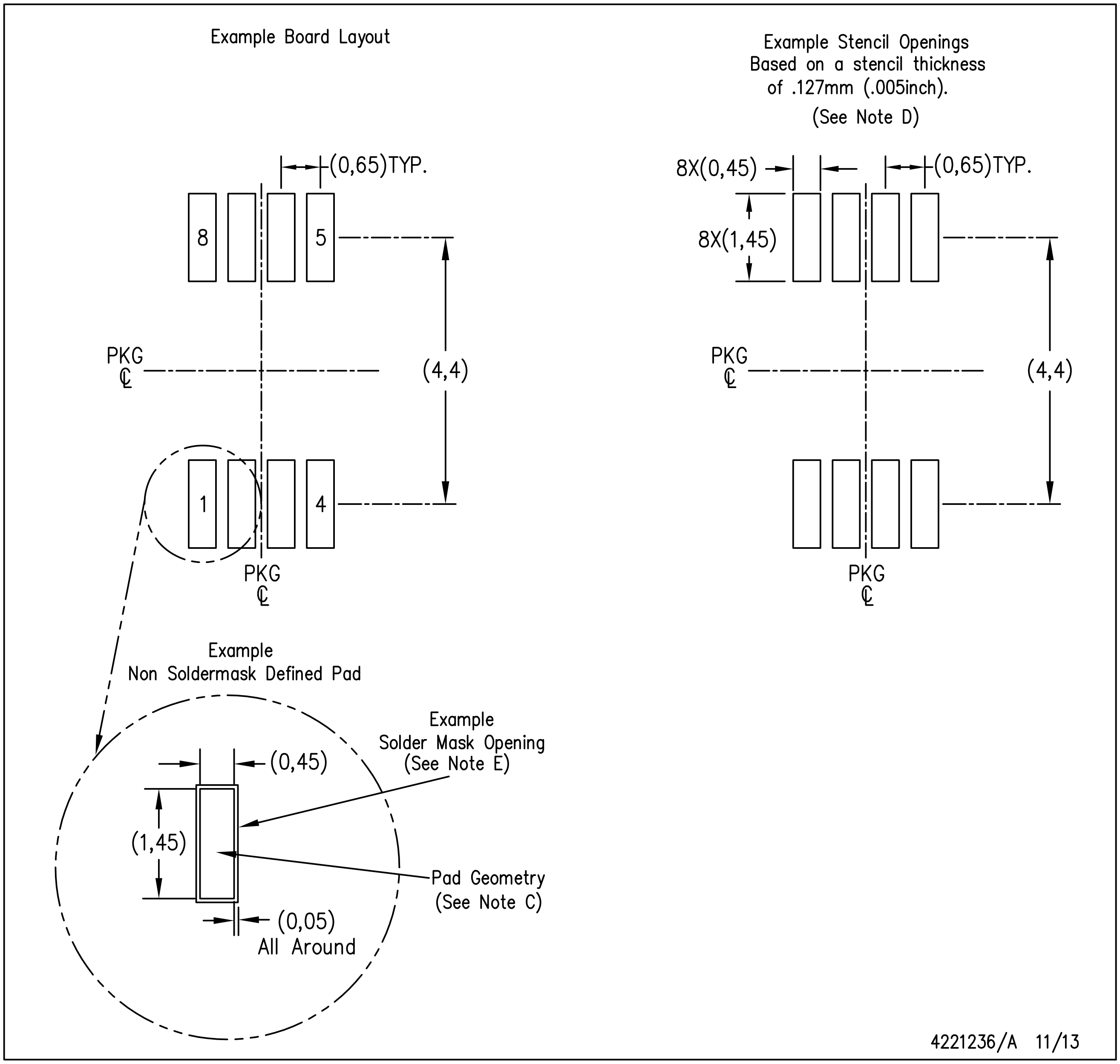
NOTES:
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS–001 variation BA.

DGK (S–PDSO–G8) PLASTIC SMALL–OUTLINE PACKAGE



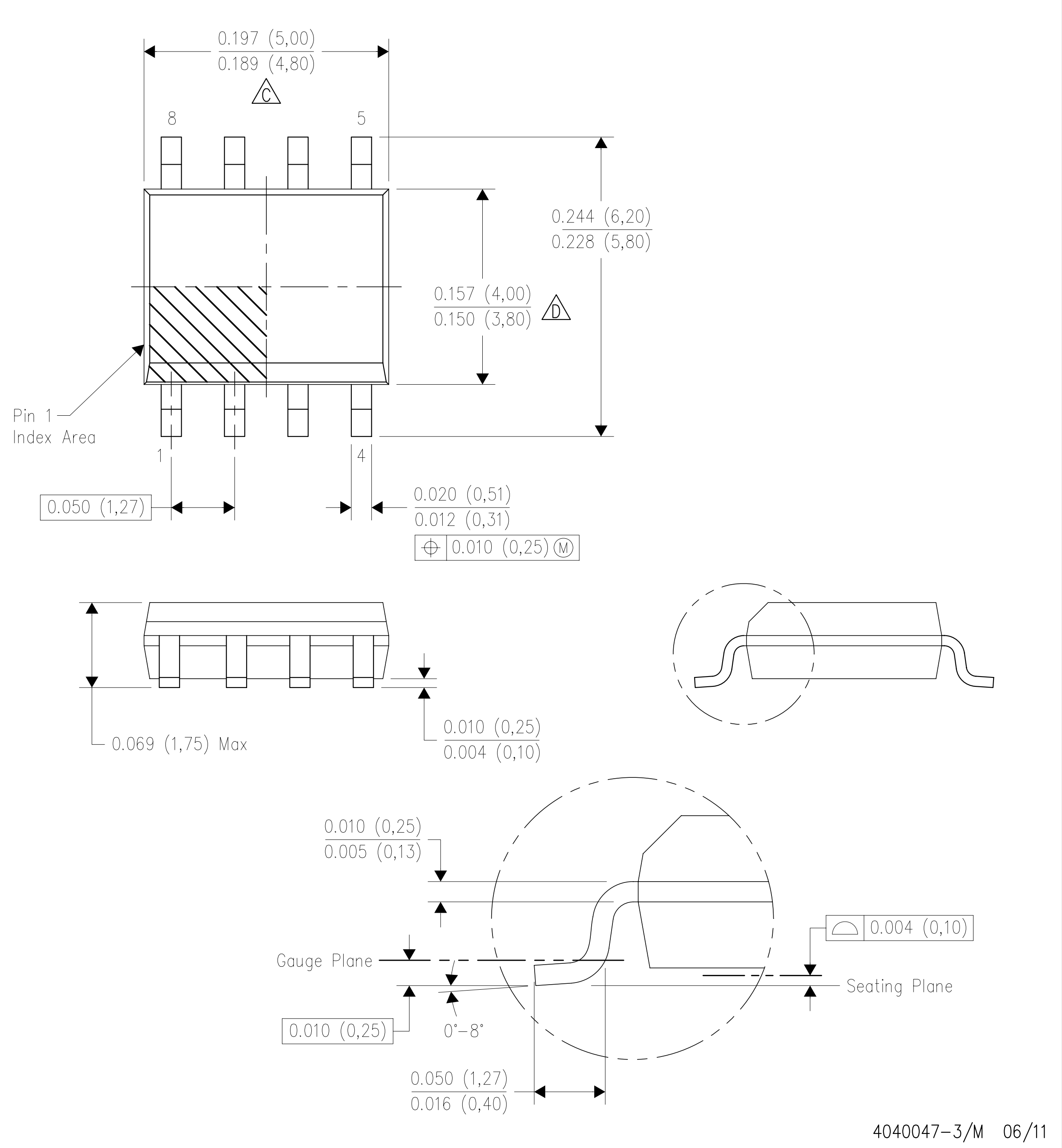
NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C▷ Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 per end.
D▷ Body width does not include interlead flash. Interlead flash shall not exceed 0.50 per side.
E. Falls within JEDEC MO–187 variation AA, except interlead flash.

DGK (S-PDSO-G8) PLASTIC SMALL OUTLINE PACKAGE



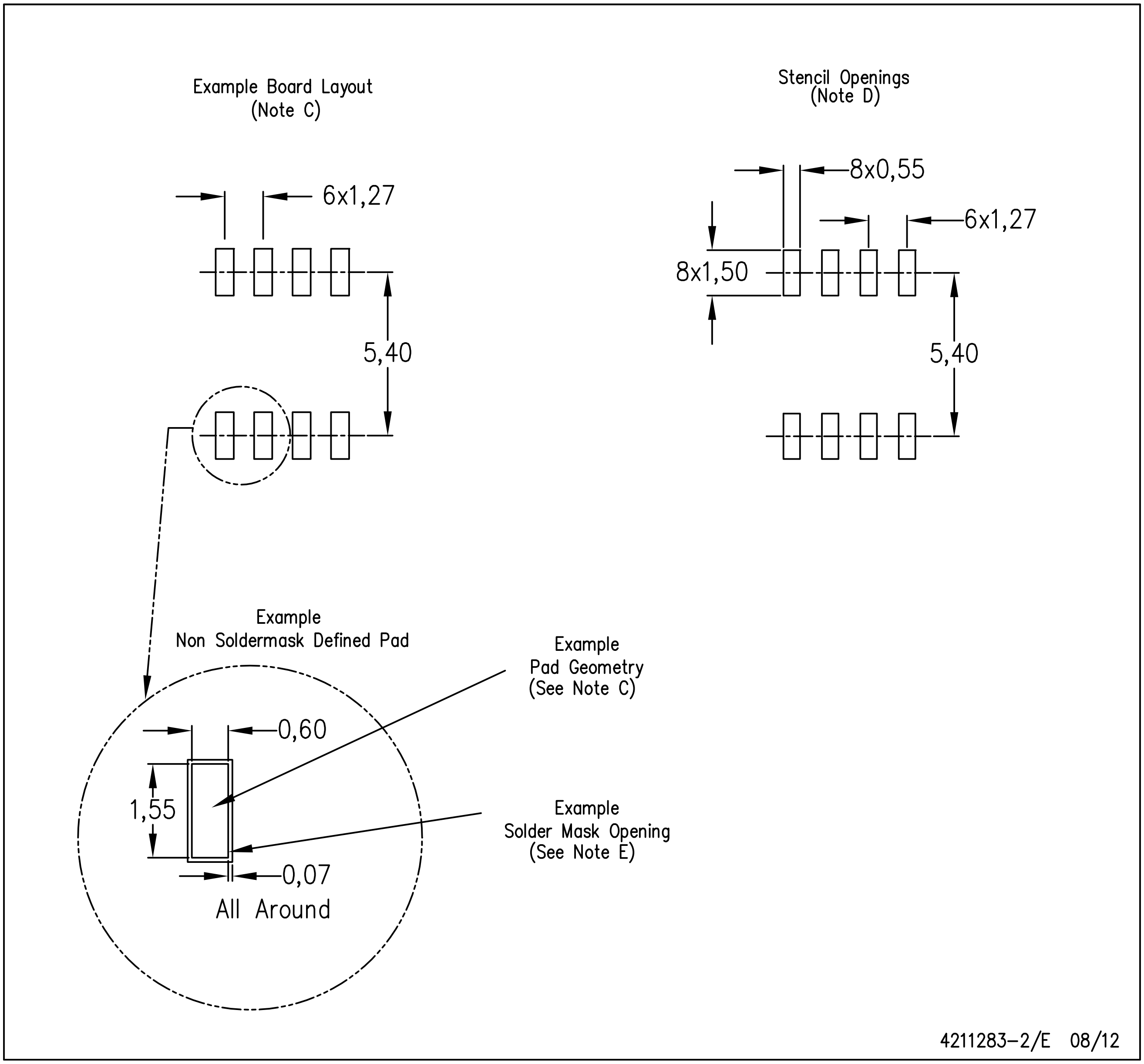
NOTES:
- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC–7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

D (R–PDSO–G8) PLASTIC SMALL OUTLINE



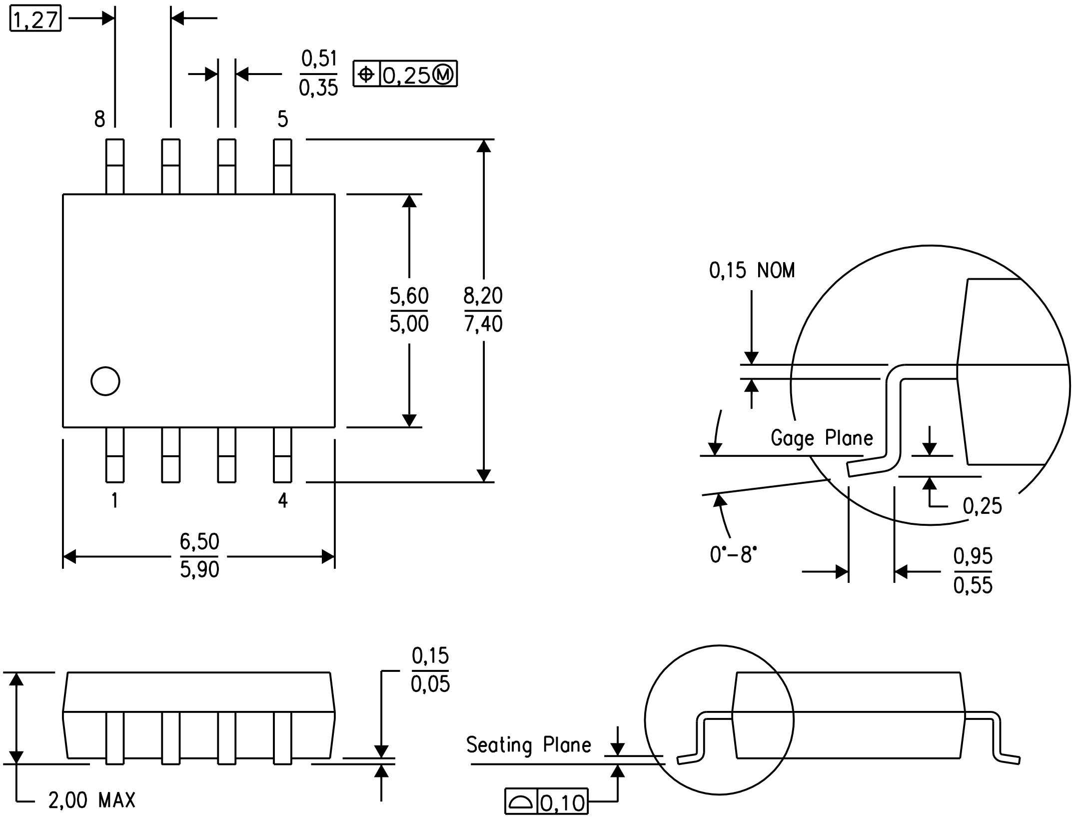
NOTES:
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS–012 variation AA.

D (R–PDSO–G8) PLASTIC SMALL OUTLINE



NOTES:
- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC–7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

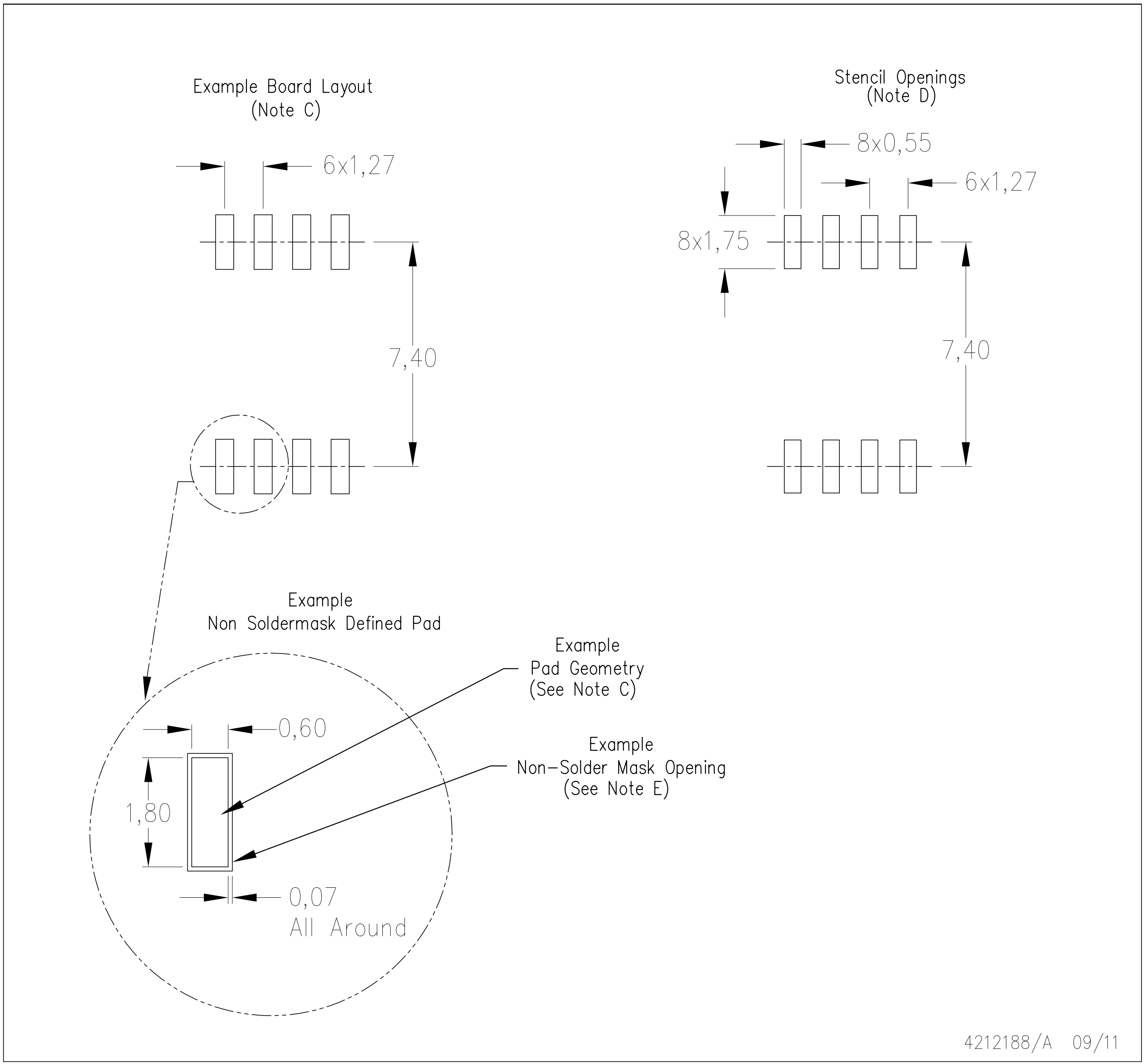
PS (R-PDSO-G8) PLASTIC SMALL-OUTLINE PACKAGE



4040063/C 03/03

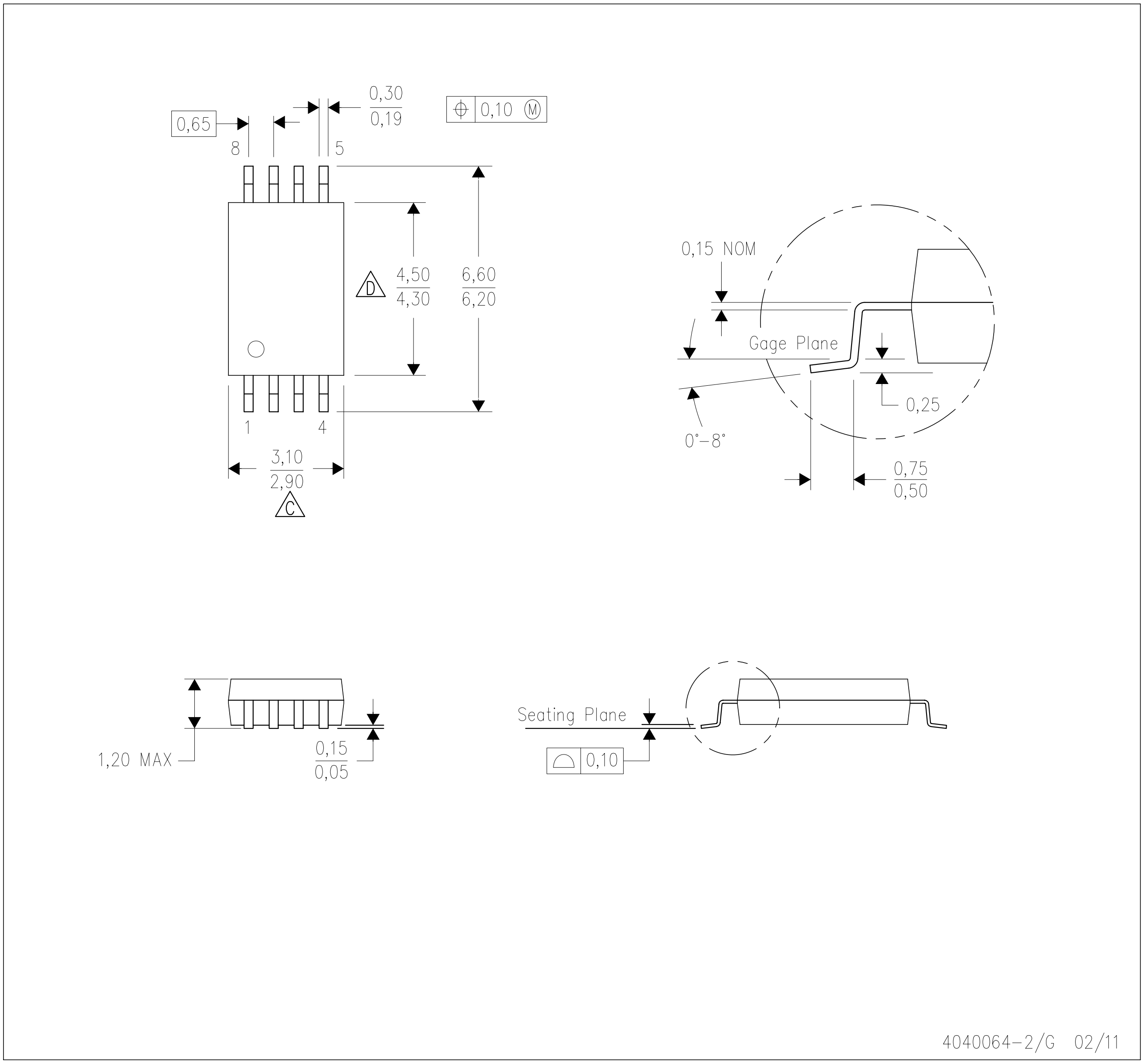
NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

PS (R-PDSO-G8) PLASTIC SMALL OUTLINE



NOTES:
- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC–7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PW (R–PDSO–G8) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M–1994.
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
E. Falls within JEDEC MO–153

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